

## RAD-TOLERANT SPACE GRADE DIE, PRECISION PROGRAMMABLE REFERENCE

 Check for Samples: [TL1431-DIE](#)

### FEATURES

- QMLV Qualified to 100k Rad RHA, SMD 5962R99620
- Initial Voltage Tolerance
- 0.2-Ω Typical Output Impedance
- Fast Turnon...500 ns
- Sink Current Capability
- Low Reference Current (REF)
- Adjustable Output Voltage

### DESCRIPTION

The TL1431-DIE is a precision programmable reference. This device has a typical output impedance of 0.2 Ω. Active output circuitry provides a very sharp turnon characteristic, making the device an excellent replacement for Zener diodes and other types of references in applications such as onboard regulation, adjustable power supplies, and switching power supplies.

### ORDERING INFORMATION<sup>(1)</sup>

PRODUCT	PACKAGE DESIGNATOR	PACKAGE	ORDERABLE PART NUMBER	PACKAGE QUANTITY
TL1431V	TD	Bare die in waffle pack <sup>(2)</sup>	TL1431VTDB1	100
			TL1431VTDB2	10

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).
- (2) Processing is per the Texas Instruments space production baseline and is in compliance with the Texas Instruments Quality Control System in effect at the time of manufacture. Electrical screening consists of DC parametric and functional testing at room temperature only. Unless otherwise specified by Texas Instruments AC performance and performance over temperature is not warranted. Visual Inspection is performed in accordance with MIL-STD-883 Test Method 2010 Condition B at 75X minimum.



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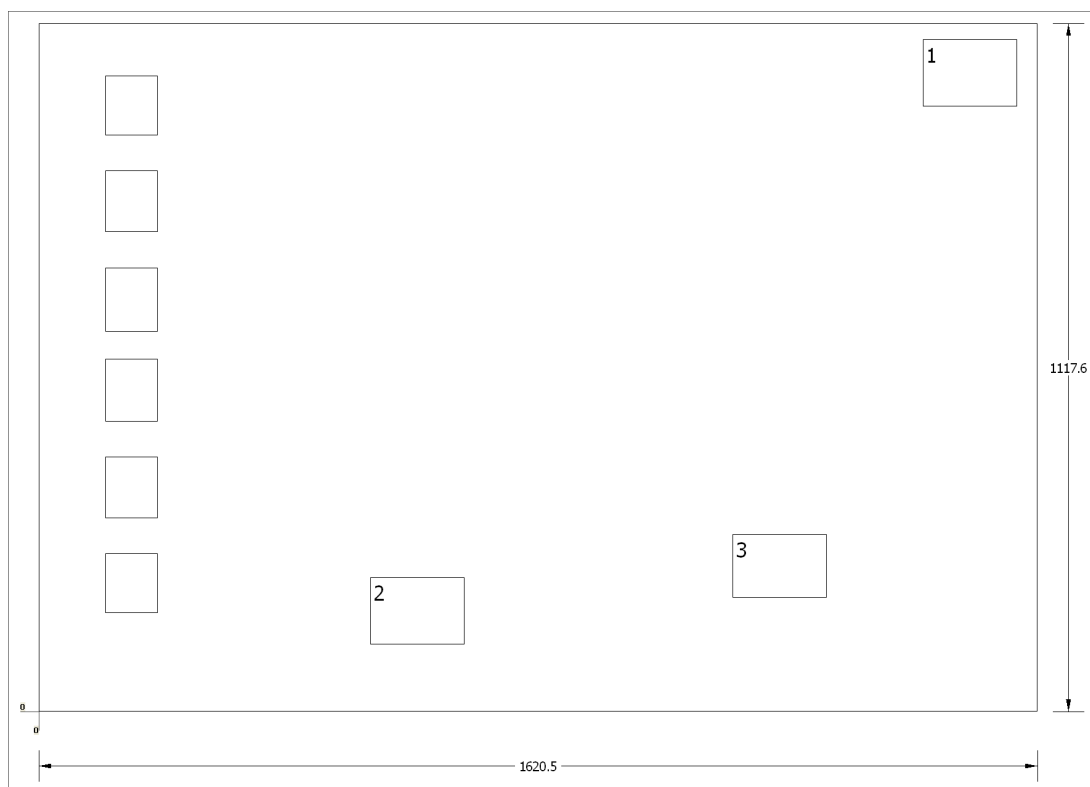


This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### BARE DIE INFORMATION

DIE THICKNESS	BACKSIDE FINISH	BACKSIDE POTENTIAL	BOND PAD METALLIZATION COMPOSITION	BOND PAD THICKNESS
10.5 mils.	Silicon with backgrind	Floating	TiW/AlCu2%	1626.9 nm



**Table 1. Bond Pad Coordinates in Microns**

DESCRIPTION	PAD NUMBER	X MIN	Y MIN	X MAX	Y MAX
CATHODE	1	1435.1	982.98	1587.5	1092.2
ANODE	2	538.48	109.22	690.88	218.44
REF	3	1126.49	185.42	1278.89	288.29

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL1431VTDB1	ACTIVE			0	100	TBD	Call TI	N / A for Pkg Type	25 to 25		<b>Samples</b>
TL1431VTDB2	ACTIVE			0	10	TBD	Call TI	N / A for Pkg Type	25 to 25		<b>Samples</b>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF TL1431-DIE :**

- Automotive: [TL1431-Q1](#)
- Enhanced Product: [TL1431-EP](#)
- Space: [TL1431-SP](#)

## NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

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